

ELECTROLESS PLATING PROCESS

Abstract

5 An object is to provide an electroless plating
process which can thin a film thickness of a nickel film
and can obtain a film having excellent mounting
characteristics, when the nickel film and a gold film are
sequentially formed on a surface of a copper material.

10 In order to solve the above-mentioned problems, provided
is an electroless plating process which sequentially
forms a nickel film and a gold film on a surface of a
copper material by an electroless plating method and
includes: a step of forming the nickel film on the

15 surface of the copper material by an electroless strike
plating method; and a step of forming the gold film by a
reduction-type electroless plating method.

20 Figure 1